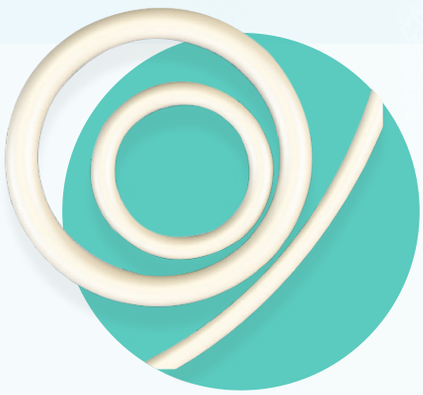
PERFREZ® Elastomers

Purity Solution for Both Static and Dynamic Applications

PERFREZ® XL15 is a translucent compound made of a semicrystalline nano-filler. This compound is developed to handle the most demanding fluorine, chlorine and oxygen plasmas as well as the most aggressive acids and solvents used in semiconductor processing. It is also recommended for extreme applications in the bio-analytical industry.

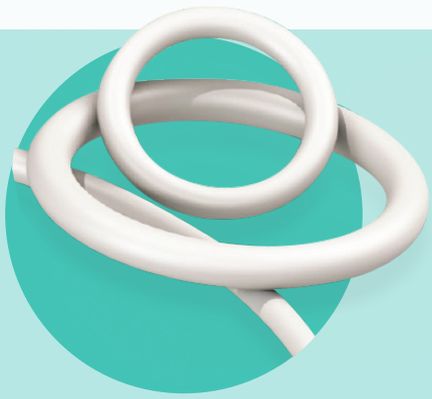


Purity Solution for Both Static and Dynamic Applications

PERFREZ® XL12 features superior physical properties with exceptionally low particle generation. XL12 offers a low Coefficient of Thermal Expansion (CTE) that mitigates risk of extrusion, while offering outstanding plasma resistance and erosion, especially with aggressive fluorine based process.

Enhanced Plasma Resistance and Physical Strength

PERFREZ® XL11 offers superior plasma resistance especially aggressive fluorine based process. It also features the excellent physical properties with low CTE that mitigate any risk of extrusion due to thermal expansion.

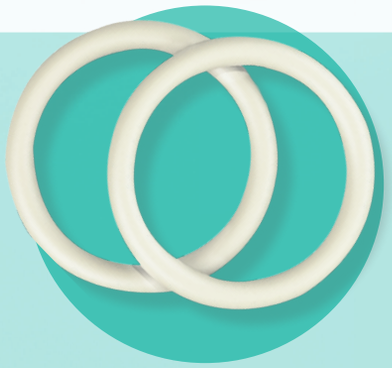


High Temperature Perfluoroelastomer That Combines The Benefits of Chemical Compatibility with Thermal Stability for Sub-Fab Applications

PERFREZ® 6022 is specially developed to handle aggressive oxygen and fluorine based exhaust gases while providing excellent thermal properties.

Specialty Hybrid - Ideal and Economic Solution for Better Performance

PERFREZ® 5033 solves the problem where an FKM (known as Viton® in all their many mixes and grades) cannot handle the process chemistries but a FFKM (perfluoroelastomer) is an 'overkill' solution.



High Temp. Perfluoroelastomer for Plasma Applications

PERFREZ® MX30 expands the MX series, being specially developed to handle extreme high temperatures combined with aggressive oxygen-based plasma, while generating minimal particles. MX30 features low compression set, and greater resilience against excessive stress during operation, making it exceptionally capable for challenging seal locations.

Ultra Pure FFKM for Harsh Semiconductor Applications

PERFREZ® PXC-Ultra a high purity upgrade of PXC which is also specialized for semiconductor equipment with harsh conditions, especially with stringent requirement on contamination. As effective as the original version, it also offers excellent resistance to a wide variety of chemistries including acids/bases which makes it a great alternative for wet applications, while keeping the same temperature endurance.

High Performance Seal Solution for Harsh Semiconductor Applications

PERFREZ® PXC is a specialized line of Perfluoroelastomers for semiconductor equipment wet manufacturing processes. PXC offers excellent resistance to a wide variety of chemistries including acids/bases. PXC has a maximum service temperature of 260°C.

High Temperature FFKM for Static Seal Applications

PERFREZ® MX20 is a high-performance FFKM designed to meet extreme heat requirements within the Fab and Sub-Fab. MX20 features great resilience, superior compression set, and low thermal expansion to minimize thermal degradation and seal extrusion. With its broad chemical compatibility, MX20 presents an ideal sealing solution for the harsh chemical environments found in forelines, exhausts, pumps, and valves.

Note:

Slight color variations may be observed in actual ASNA products (seals / bonded gates). Variations are considered to be normal phenomena in seal manufacturing.
Due to the curing process, small marks or dark spots may be observed in actual ASNA products. It is not indicative of foreign matter and will not impact on product performance.
Please contact ASNA engineers if there are any questions or concerns.

PERFREZ®
faith in precision